

In the Claims:

Please cancel Claims 8, 10, 12-16 and 31-36, without prejudice, and amend

Claims 1, 3 and 5 as follows:

*Sub C1*

*B4*

1. (Once Amended) An embedded electroconductive layer comprising:  
a depressed part formed in an insulating film on a substrate;  
a barrier layer covering said depressed part;  
a metal growth promoting layer on said barrier layer, said metal growth  
promoting layer being made of a material different from that of said barrier layer; and  
an electroconductive layer embedded in said depressed part via said  
barrier layer and said metal growth promoting layer.

*Sub C2*

*B5*

3. (Twice Amended) The embedded electroconductive layer according to  
claim 1 wherein said metal growth promoting layer is a TiN layer containing oxygen at a  
lower concentration than said barrier layer.

*Sub C2*

*B6*

5. (Once Amended) An embedded electroconductive layer comprising:  
a depressed part formed in an insulating layer on a substrate;  
a ground layer containing oxygen at a high concentration in the lower  
part thereof and at a low concentration in the upper part thereof due to removal of oxygen